

RV1S9161A

15 Mbps, HIGH CMTI, IPM DRIVER, 5-PIN SOP PHOTOCOUPLER

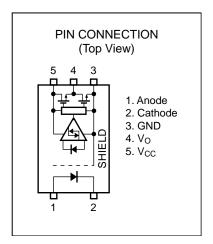
R08DS0271EJ0100 Rev.1.00 May 09, 2022

DESCRIPTION

The RV1S9161A is a photocoupler featuring high-speed switching up to 15 Mbps with active high output logic which consists of an AlGaAs LED on the input side and an integrated circuit with a photodiode on the output. The RV1S9161A is designed specifically for high common mode transient immunity (CMTI), wide operating power supply voltage range and high temperature operation up to $T_A = 125$ °C. It is suitable for IPM (Intelligent Power Module) drive.

FEATURES

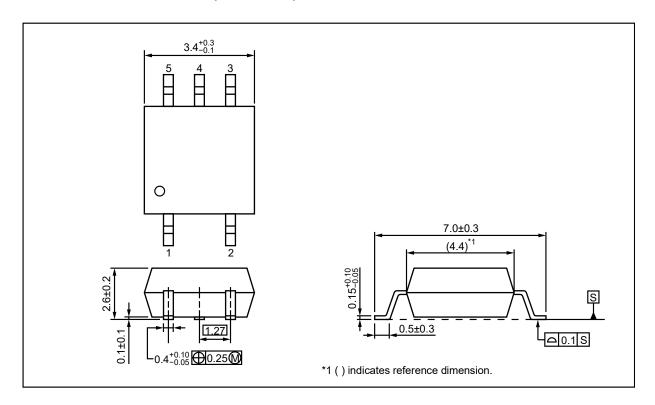
- High speed switching (15 Mbps)
- High common mode transient immunity (CM_H, CM_L = ± 100 kV/ μ s MIN.)
- Pulse width distortion (|tphl tplh| = 20 ns MAX.)
- Wide operating power supply voltage range (Vcc = 4.5 ~ 30 V)
- Operating ambient temperature (125 °C MAX.)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- Embossed tape product: RV1S9161ACCSP-100x#KC0: 2 500 pcs/reel
- Pb-Free product
- Safety standard
 - UL : UL1577, Double protection
 - CSA: CAN/CSA-C22.2 No.62368-1, Reinforced insulation
 - VDE : DIN EN 60747-5-5 (Option)



APPLICATIONS

- IPM driver
- General purpose inverter

PACKAGE DIMENSIONS (UNIT: mm)

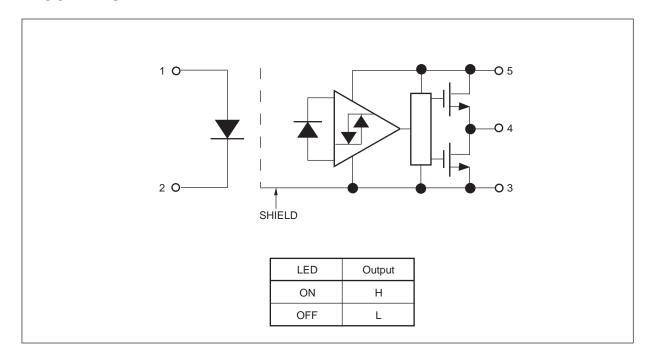


Weight: 0.08 g (Typ.)

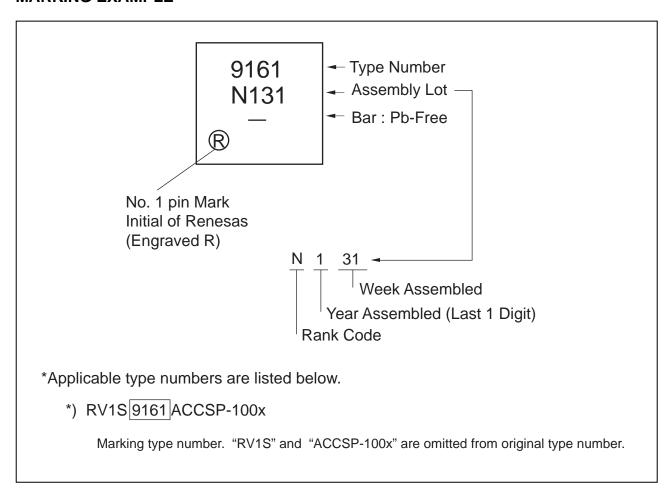
PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4.2 mm
Creepage Distance	4.2 mm
Isolation Distance	0.2 mm

BLOCK DIAGRAM



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification			Application Part Number *1
RV1S9161ACCSP	RV1S9161ACCSP	Pb-Free and	20 pcs	Standard products	RV1S9161A
-100C	-100C#SC0	Halogen Free	(Tape 20 pcs cut)	(UL, CSA approved)	
	RV1S9161ACCSP	(Ni/Pd/Au)	Embossed Tape		
	-100C#KC0		2 500 pcs/reel		
RV1S9161ACCSP	RV1S9161ACCSP		20 pcs	UL, CSA,	
-100V	-100V#SC0		(Tape 20 pcs cut)	DIN EN 60747-5-5	
	RV1S9161ACCSP		Embossed Tape	approved	
	-100V#KC0		2 500 pcs/reel		

Notes:*1. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current *1	IF	20	mA
	Reverse Voltage	V _R	5	V
Detector	Supply Voltage	V _{CC}	-0.5 to +30	V
	Output Voltage	Vo	-0.5 to Vcc	V
	Output Current	lo	25	mA
	Power Dissipation *2	Pc	200	mW
Isolation Voltage*3		BV	3 750	Vr.m.s.
Operating Ambient Temperature		T _A	-40 to +125	°C
Storage Temperature		T _{stg}	−55 to +150	°C

Notes: *1. Reduced to 0.93 mA/°C at $T_A = 110$ °C or more.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	4.5		30	V
Forward Current (ON)	I _{F (ON)}	5		12	mA
Forward Voltage (OFF)	V _F (OFF)	0		0.8	V
Supply Voltage Ramp Slew Rate	SR			0.5	V/µs
Operating Ambient Temperature	TA	-40		125	°C

^{*2.} Reduced to 4.57 mW/°C at $T_A = 90$ °C or more.

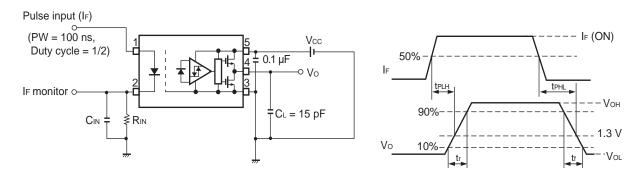
^{*3.} AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output. Pins 1-2 shorted together, 3-5 shorted together.

ELECTRICAL CHARACTERISTICS ($T_A = -40 \text{ to } +125 \text{ °C}$, $V_{CC} = 4.5 \text{ to } 30 \text{ V}$)

	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA, T _A = 25 °C	1.33	1.54	1.73	V
	Reverse Current	I_R	V _R = 3 V, T _A = 25 °C			10	μΑ
	Input Capacitance	Ct	V _F = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Voltage	V _{OH}	$I_F = 5 \text{ mA}, I_O = -3.5 \text{ mA}$	V _{CC} -1.5			V
			$I_F = 5 \text{ mA}, I_O = -6.5 \text{ mA}$	Vcc-2.0			
	Low Level Output Voltage	V_{OL}	$I_F = 0 \text{ mA}, I_O = 3.5 \text{ mA}$			0.3	V
			$I_F = 0 \text{ mA}, I_O = 6.5 \text{ mA}$			0.5	
	High Level Supply Current	Іссн	$I_F = 5 \text{ mA}, V_{CC} = 30 \text{ V}$		1.7	3	mA
	Low Level Supply Current	Iccl	$I_F = 0$ mA, $V_{CC} = 30$ V		1.7	3	mA
	UVLO Threshold	V_{UVLO}	Vo < 1 V,		3		V
			I _F = 5 ~ 12 mA				
Coupled	Threshold Input Current	I_{FLH}	$V_{CC} = 15 \text{ V}, V_O > 13.5 \text{ V},$			3.0	mA
	$(L \rightarrow H)$		$I_0 = -3.5 \text{ mA}$				
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1 \text{ kV dc}, \text{ RH } \leq 60\%,$	10 ¹¹			Ω
			T _A = 25 °C				
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		0.6		pF
	Propagation Delay Time	t _{PLH}	$V_{IN} = 0 \rightarrow 5 \text{ V}, C_{IN} = 60 \text{ pF},$			60	ns
	$(L \rightarrow H)^{*2}$		$R_{IN} = 650 \ \Omega, \ C_L = 15 \ pF,$				
			V _{THLH} = 1.3 V				
	Propagation Delay Time	t PHL	$V_{IN} = 5 \rightarrow 0 \text{ V}, C_{IN} = 60 \text{ pF},$			60	ns
	$(H \rightarrow L)^{*2}$		$R_{IN} = 650 \Omega, C_L = 15 pF,$				
			V _{THHL} = 1.3 V				
	Pulse Width Distortion	t _{PHL} -t _{PLH}	$V_{IN} = 0 \Leftrightarrow 5 \text{ V}, C_{IN} = 60 \text{ pF},$			20	ns
	PWD)	,	$R_{IN} = 650 \Omega, C_L = 15 pF,$				4
	Propagation Delay		VTHLH=VTHHL= 1.3 V			25	
	Difference Between Any Two Parts (PDD)						
	Common Mode Transient	CM _H	V _{CC} = 30 V, T _A = 25 °C,	100			kV/μs
	Immunity at High Level	IOIVIHI	V _{CC} = 30 V, T _A = 25 C, V _O > 17 V.	100			κν/μδ
	Output *3		$ I_F = 5 \text{ mA}, V_{CM} = 1.5 \text{ kV}$				
	Common Mode Transient	CM _L	$V_{CC} = 30 \text{ V}, T_A = 25 \text{ °C},$	100			kV/μs
	Immunity at Low Level	101	Vo < 1 V,				,
	Output *3		$I_F = 0 \text{ mA}, V_{CM} = 1.5 \text{ kV}$				

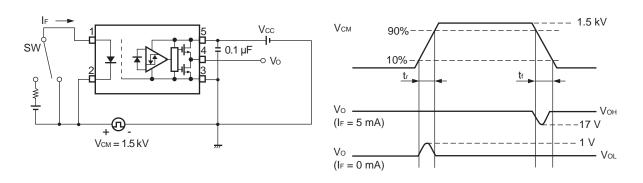
Notes: *1. Typical values at $T_A = 25$ °C.

*2. Test circuit for propagation delay time

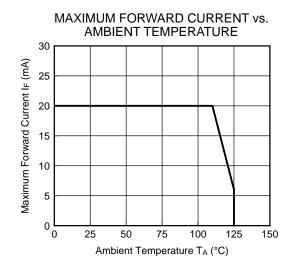


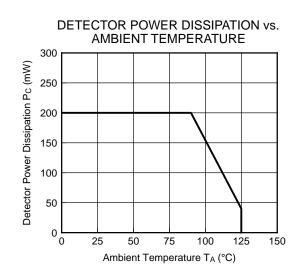
Remark C_L includes probe and stray wiring capacitance.

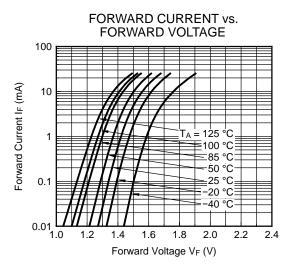
*3. Test circuit for common mode transient immunity

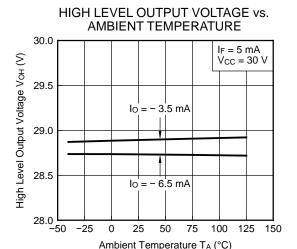


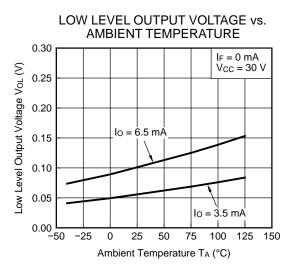
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

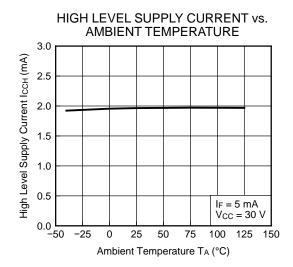






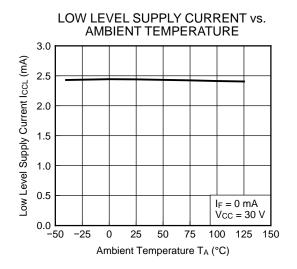


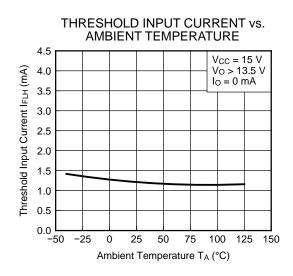


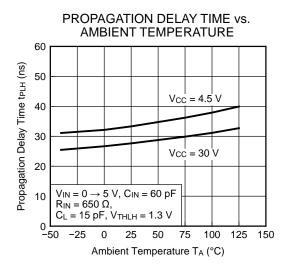


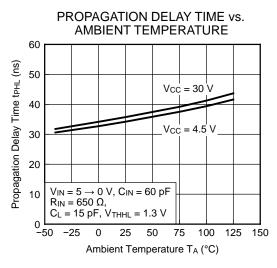
Remark The graphs indicate nominal characteristics.

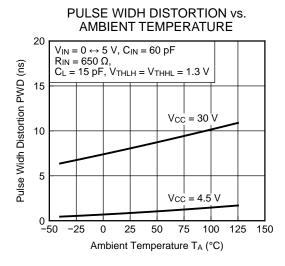
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

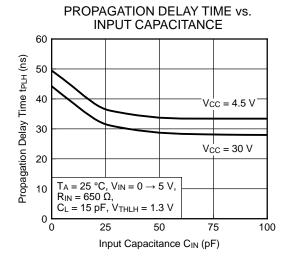






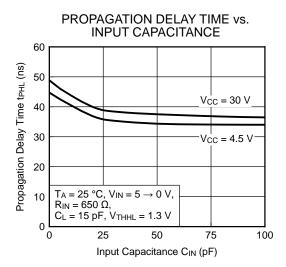






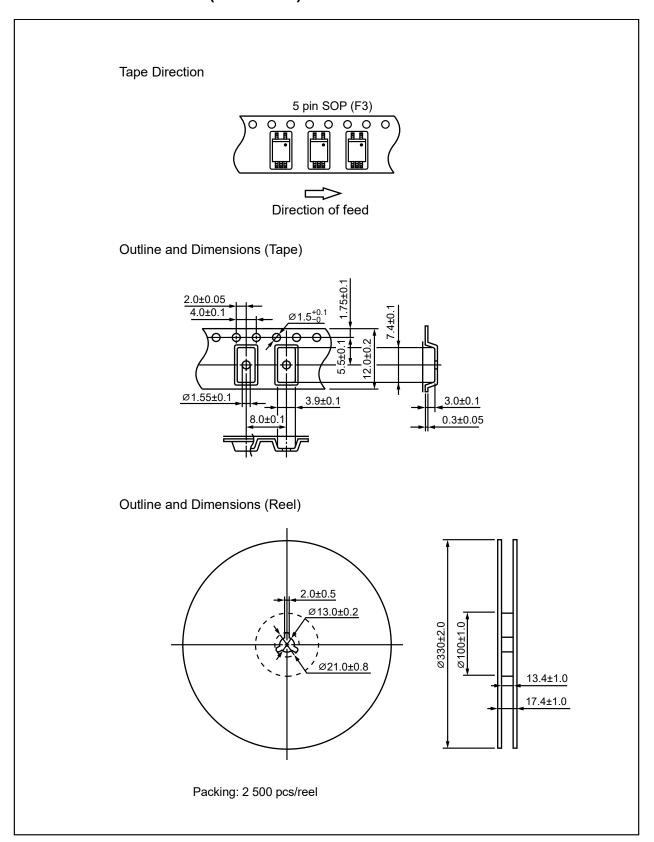
Remark The graphs indicate nominal characteristics.

TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

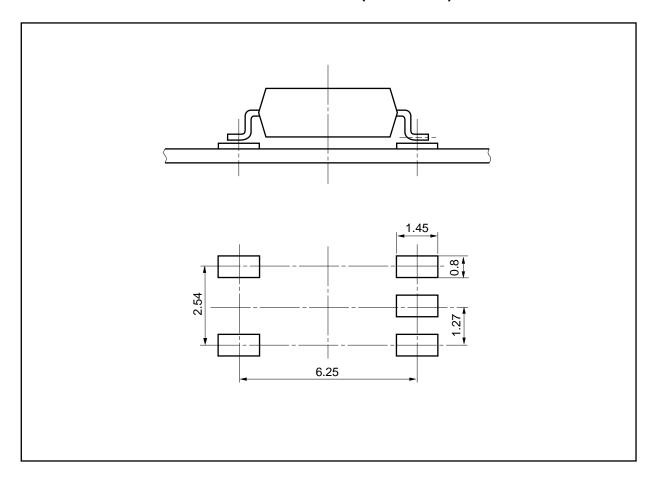


Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering
 - Peak reflow temperature
 - Time of peak reflow temperature -5 °C (255 °C)
 - Time of temperature higher than 217 °C
 - Time to preheat temperature from 150 to 200 °C
 - Number of reflows
 - Flux

260 °C or below (package surface temperature)

30 seconds or less

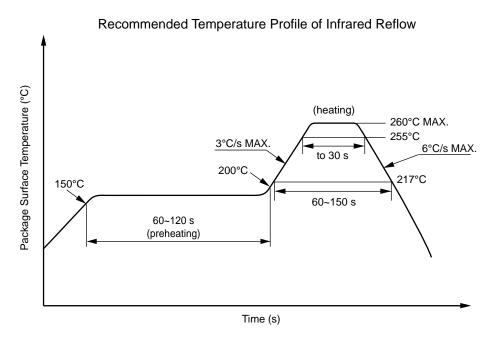
60~150 seconds

60~120 seconds

Three

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt% is recommended.)



JEDEC J-STD-020D compliant soldering conditions

(2) Wave soldering

• Temperature 260 °C or below (molten solder temperature)

Time 10 seconds or less

Preheating conditions 120 °C or below (package surface temperature)

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

Peak Temperature (lead part temperature)
 Time (each pins)
 350 °C or below
 3 seconds or less

Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(4) Cautions

Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

Do not use fixing agents or coatings containing halogen-based substances.

RV1S9161A Data Sheet

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

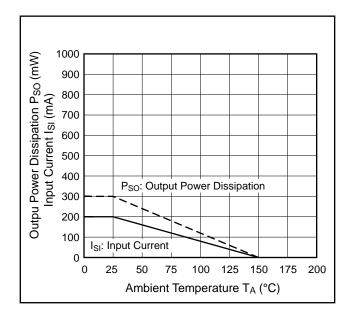
USAGE CAUTIONS

- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than 0.1 μ F is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.

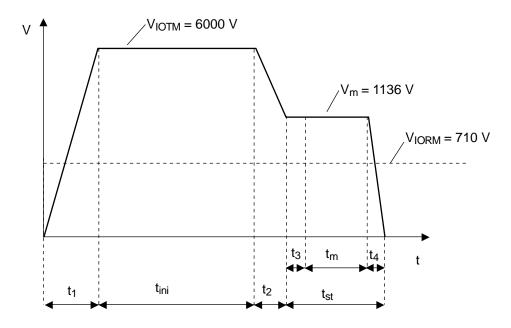
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/125/21	
Dielectric strength			
maximum operating isolation voltage	Viorm	710	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random	V _m	1 136	V_{peak}
test)			
$V_m = 1.6 \times V_{IORM.}, q_{pd} < 5 pC$			
Test voltage (partial discharge test, procedure b for all devices)	V _m	1 331	V_{peak}
$V_m = 1.875 \times V_{IORM.}, q_{pd} < 5 pC$	V m	1 331	∨ peak
Highest permissible overvoltage	V _{ІОТМ}	6 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	400	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		П	
Storage temperature range	T _{stg}	-55 ~ +150	°C
Operating temperature range	TA	-40~+125	°C
Isolation resistance, minimum value			
V _{I-O} = 500 V dc, T _A = 25 °C	R _{I-O} MIN.	10 ¹²	Ω
$V_{I\text{-}O}$ = 500 V dc, T_A = maximum temperature of rating, at least 100 °C	R _{I-O} MIN.	10 ¹¹	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal			
derating curve)			
Maximum ambient temperature	Ts	150	°C
Maximum input current	Isı	200	mA
Maximum output power dissipation	Pso	300	mW
Isolation resistance, minimum value at $V_{I-O} = 500 \text{ V}$ dc, $T_A = T_S$	R _{I-O} MIN.	10 ⁹	Ω

Dependence of maximum safety ratings on ambient temperature



Method a) Destructive Test, Type and Sample Test



 t_1 , $t_2 = 1$ to 10 sec

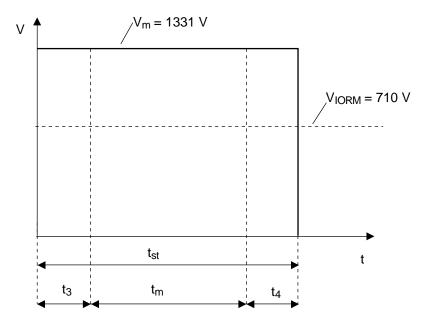
 t_3 , $t_4 = 1$ sec

 $t_{m} = 10 \text{ sec}$

 $t_{st} = 12 \text{ sec}$

 $t_{ini} = 60 \text{ sec}$

Method b) Non-destructive Test, 100% Production Test



 t_3 , $t_4 = 0.1 \text{ sec}$

 $t_m = 1.0 \text{ sec}$

 $t_{st} = 1.2 \text{ sec}$

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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